

## **Specification Sheet**

P/N: MSCDRI-4D28C-SERIES-RU

Products: Certifications:

Molded Power Chokes ISO9001

Multilayer Chip Inductors IATF16949

<u>Lan Transformer</u> ISO14001

RF Passive / Antennas QC080000

**Automotive** 

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#### **SCOPE:**

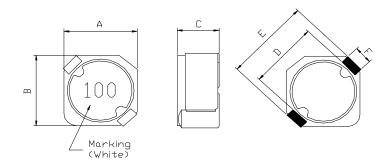
This specification applies to the Pb Free high current type SMD inductors for MSCDRI-4D28C-SERIES

#### PRODUCT INDENTIFICATION

MSCDRI - 4D28C - 100 M-RU

- (1)
- 2
- 3 4
- **1** Product Code
- 2 Dimensions Code
- **3 Inductance Code**
- **4** Tolerance Code

#### (1) SHAPES AND DIMENSIONS



A: 5.10 Max. mm
B: 5.10 Max. mm
C: 3.00 Max. mm
D: 4.40 Typ. mm
E: 6.20 Max. mm
F: 1.40 Typ. mm

## (2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

**TEST INSTRUMENTS** 

L: HP 4284A PRECISION LCR METER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

#### (3) CHARACTERISTICS

(3)-1 Ambient temperature ......  $+60^{\circ}$ C Max.

(3)-2 Operate temperature range ......  $-40^{\circ}$ C  $\sim +125^{\circ}$ C (Including self temp. rise)

(3)-3 Storage temperature range ......  $-40^{\circ}$ C  $\sim +125^{\circ}$ C



**TABLE 1** 

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated DC Current	Morking	
PT/NO.	L(µH)	Tolerance	Frequency	RDC(Ω)Max.	IDC(A)	Marking	
MSCDRI-4D28C-1R1□-RU	1.1	N	100kHz/0.25V	22m	3.80	1R1	
MSCDRI-4D28C-2R0□-RU	2.0	M,N	100kHz/0.25V	29m	2.60	2R0	
MSCDRI-4D28C-3R2□-RU	3.2	N	100kHz/0.25V	42m	2.30	3R2	
MSCDRI-4D28C-4R7□-RU	4.7	M,N	100kHz/0.25V	63m	1.80	4R7	
MSCDRI-4D28C-6R3□-RU	6.3	N	100kHz/0.25V	94m	1.30	6R3	
MSCDRI-4D28C-100□-RU	10	M,N	100kHz/0.25V	0.106	1.26	100	
MSCDRI-4D28C-150□-RU	15	M,N	100kHz/0.25V	0.137	1.05	150	
MSCDRI-4D28C-220□-RU	22	M,N	100kHz/0.25V	0.207	0.85	220	
MSCDRI-4D28C-330□-RU	33	M,N	100kHz/0.25V	0.331	0.70	330	
MSCDRI-4D28C-470□-RU	47	M,N	100kHz/0.25V	0.510	0.54	470	
MSCDRI-4D28C-680-□-RU	68	M,N	100kHz/0.25V	0.625	0.49	680	
MSCDRI-4D28C-101□-RU	100	M,N	100kHz/0.25V	0.948	0.40	101	

**<sup>※</sup>** ☐ specify the inductance tolerance,M(±20%),N(±30%)

%IDC : Based on inductance change ( $\triangle$ L/Lo : drop 35% max) @ ambient temp. 25 $^{\circ}$ C and Based on temperature rise ( $\triangle$ T : 40 $^{\circ}$ C TYP.)



# (4) RELIABILITY TEST METHOD MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS			
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		in figure 1 and a load applied unitil the figure in the arrow			
	There shall be	direction is made approximately 3mm.(keep time 30 seconds)			
	no mechanical	PCB dimension shall the page 7/9			
	damage or elec-	F(Pressurization)			
	trical damege.	$\Box$			
		R5 45±2 45±2 10 20			
		PRESSURE ROD			
Vibration	△L/Lo≦±5%	figure-1  The sample shall be soldered onto the printed circuit board			
		and when a vibration having an amplitude of 1.52mm			
	There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should			
	no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.			
	damage.	(A total of 6 hours)			
	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated			
Solderability	More than 90%	over the whole of the sample before hard, the sample shall			
	Wiore than 30 %	then be preheated for about 2 minutes in a temperature of			
		130~150°C and after it has been immersed to a depth 0.5mm			
		below for 3±0.2 seconds fully in molten solder M705 with			
		a temperature of 245±5℃.			
		More than 90% of the electrode sections shall be couered			
	1	with new solder smoothly when the sample is taken out of			



#### **MECHANICAL**

TEST ITEM		SPECIFICATION				
TEST ITEM Resistance to Soldering heat (reflow soldering)	There shall be no damage or problems.	Temperature profile of reflow soldering  soldering  soldering  (Peak temperature 260±3°C 10 sec  a) 30 sec Min (230°°°C)				
		Slow cooling				
		The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time.				
		The specimen shall be stored at standard atmospheric conditions for 1 hour, after which the measurement shall be made.				

#### **ELECTRICAL**

TEST ITEM	SPECIFICATION	TEST DETAILS
Insulation	There shall be	DC 100V voltage shall be applied across this sample of top
resistance	no other	surface and the terminal.
	damage or	The insulation resistance shall be more than 1 $\times$ 10 <sup>8</sup> $\Omega$ .
	problems.	
Dielectric	There shall be	AC 100V voltage shall be applied for 1 minute acrosset the top
withstand	no other	surface and the terminal of this sample
voltage	damage or	
	problems.	
Temperature	∆L/L20°C ≦±10%	The test shall be performed after the sample has stabilized in
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85℃,and the value
		calculated based on the value applicable in a normal
		temperature and narmal humidity shall be △L/L20°C ≦±10%.



#### **ENVIROMENT CHARACTERISTICS**

High temperature storage	△L/Lo≦±5%  There shall be no mechanical damage.	a tempe	rature	nall be left for 96±4 hou of 85±2℃ and a norma	-	h	
ŭ	no mechanical	Upon co		of 85±2℃ and a norma	l humidity		
Low temperature	no mechanical	-		a temperature of 85±2℃ and a normal humidity.			
Low temperature		comple l	Upon completion of the measurement shall be made after the				
Low temperature	damage.	sample has been left in a normal temperature and normal					
Low temperature	· ·	humidity for 1 hour.					
Low temperature	A 1 /1 - < 150/	The sem	la ak	and he left for OC+4 here		:14	
•	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in an atmosphere with					
storage	<b>The same of the U.S.</b>	a temperature of -25±3°C.					
l	There shall be	Upon completion of the test, the measurement shall be made					
1	no mechanical		rmal temperature and				
<u> </u>	damage.	normal humidity for 1 hour.					
Change of	∆L/Lo≦±5%	The sample shall be subject to 5 continuos cycles, such as shown					
temperature		na- shall be made.					
l	There shall be						
	no other dama-						
l	ge of problems						
l		table					
l				Temperature	Duration		
l			1	<b>-25±3</b> ℃	30 min.		
l				(Themostat No.1)			
l			2	Standard	No.1→No.2		
l		atmospheric	-				
			3	<b>85±2</b> ℃	30 min.		
				(Themostat No.2)			
l			4	Standard	No.2→No.1		
l				atmospheric			
Moisuture storage	∆L/Lo≦±5%	The sam	ple sh	nall be left for 96±4 hour	rs in a temperature of		
1		40±2℃ and a humidity(RH) of 90~95%.					
1	There shall be	Upon completion of the test, the measurement shall be made					
1	no mechanical	after the sample has been left in a normal temperature and					
	damage.	normal humidity more than 1 hour.					
Test conditions :							
The sar	mple shall be reflow	soldered	onto	the printed circuit boar	d in every test.		

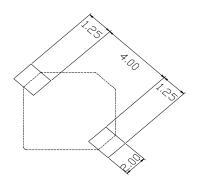


## (5) LAND DIMENSION (Ref.)

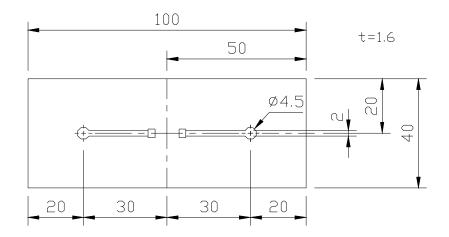
PCB: GLASS EPOXY t=1.6mm

#### (5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN) Unit: mm



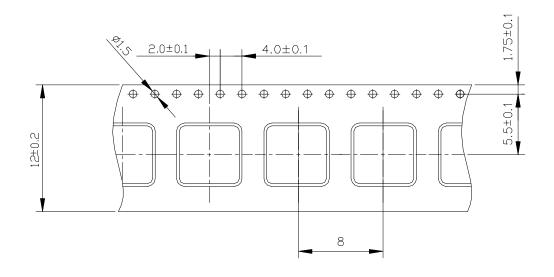
## (5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD





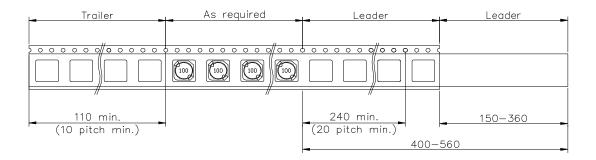
## (6) PACKAGING

## (6)-1 CARRIER TAPE DIMENSIONS (mm)



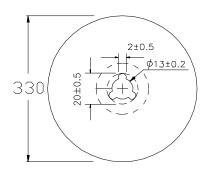
#### (6)-2 TAPING DIMENSIONS (mm)

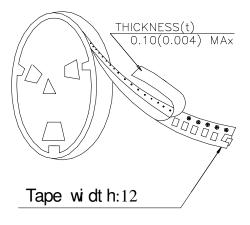






## (6)-3 REEL DIMENSIONS (mm)





## (6)-4 QUANTITY

2000pcs/Reel

The products are packaged so that no damage will be sustained.

